

ABSTRACT

The present invention relates to a technique of determining a time to replace a polishing pad used in a polishing apparatus for polishing a workpiece, such as wafer, substrate, or panel. A polishing apparatus (1) includes: a polishing table (5) configured
5 to support a polishing pad (2); a polishing head (7) configured to press a workpiece (W) against a polishing surface (2a) of the polishing pad (2); a dresser (40) configured to dress the polishing surface (2a) of the polishing pad (2); a detection sensor (60) configured to detect friction between the dresser (40) and the polishing pad (2), the detection sensor (60) being fixed to the dresser (40); and a wear monitoring device (63) configured to
10 determine a wear index value from a plurality of output values of the detection sensor (60) and generate an alarm signal when the wear index value is smaller than a predetermined lower limit.

FIG. 1